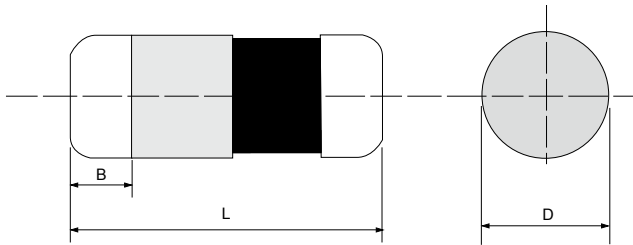


ZMM - Zero Ohm Metal Film MELF Resistor

Quality • Reliability
Cost-Down via Technology

ZMM



Specifications Per

- IEC 60115-1, IEC 60115-2

Features

- SMD enable structure
- Excellent solderability termination
- Stable metal film construction
- Products meet RoHS requirements and do not contain substances of very high concern identified by European Chemicals Agency

■ DIMENSIONS

Type	Body Length (L, mm)	Body Diameter (D, mm)	Soldering Spot (B, mm)	Net Weight Per 1000 pcs
ZMM204	3.52 ± 0.08	1.35 ± 0.1	0.6 Min.	17 grams
ZMM207	5.90 ± 0.20	2.20 ± 0.1	1.0 Min.	66 grams

■ GENERAL SPECIFICATIONS

Type	Maximum Resistance	Maximum Current
ZMM204	20mΩ	2A
ZMM207	20mΩ	4A

Special value available on request.

■ TECHNICAL SPECIFICATIONS

Characteristics	Limits	
	ZMM204	ZMM207
Insulation Voltage (1min)	>500V AC	>700V AC
Insulation Resistance	>10 ¹¹ Ω	>10 ¹¹ Ω
Operating Temperature	-55 ~ +125°C	-55 ~ +125°C
Failure Rate	<1pcs out of 10 ⁹ device hours	<1pcs out of 10 ⁹ device hours

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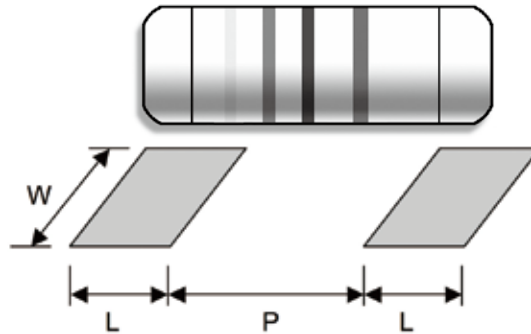
■ PART NUMBER

Example: ZMM204X000RXXXTR3K0

ZMM204	X	000R	XXX	TR3K0
Type	Tolerance Parameter Not Applicable	Resistance* 0Ω 4-character code	TCR 3-character code Parameter Not Applicable	Packaging 5-character code TR = Tape Reel (pieces per reel) ZMM204 3K0 = 3,000 6K0 = 6,000** 10K = 10,000** ZMM207 2K0 = 2,000 6K0 = 6,000** 10K = 10,000**

* Please refer to the General Specifications section of ZMM datasheet for information on maximum resistance value. **upon request

■ SUGGESTED PAD LAYOUT



Type	Soldering Mode	Pad Length (L, mm, Min.)	Pad Spacing (P, mm)	Pad Width (W, mm, Min.)
ZMM204	Reflow	1.0	2.0 ± 0.2	1.6
	Wave	1.2	2.0 ± 0.2	1.6
ZMM207	Reflow	2.0	3.0 ± 0.3	3.0
	Wave	2.5	3.0 ± 0.3	3.0

For better heat dissipation / lower heat resistance, increase W & L.

■ COVER TAPE PEELING SPECIFICATION

Recommended peeling force:

ZMM204, ZMM207: 50±5gf

